

FEATURES AND SPECIFICATIONS

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Low-profile, high-current Micro-Max Power header provides versatile solutions in a compact design

Designed for high-current density applications, Molex's Micro-Max Power header is soldered directly to PCBs such as a Voltage Regulator Module (VRM) or a mother-board using a slotted via. With a current rating of 16.0A per blade at 30°C T-rise, Micro-Max Power may be used in any board-to-board application where power transfer is needed through a non-separable interface in a compact design.

Micro-Max Power headers are available in circuit sizes ranging from 4 to 24 blades in a single-row configuration. Optional voided circuits are available, to allow for use in high-voltage applications.

Features and Benefits

- 4.17mm (.164") connector height off the PCB, the low-profile design enhances system airflow
- Compact size improves airflow and saves PCB space
- Non-separable interface allows for higher current and greater density capability with lower resistance plane-to-plane compared to similar products with separable interfaces or standard stick headers
- Optional voided circuits with design flexibility for high-voltage applications
- Two blade lengths available to accommodate 1.57 to 2.36mm (.050 to .093") PCB thicknesses

SPECIFICATIONS

Reference Information

Packaging: Tray
UL File No.: E29179
Designed In: USA

Electrical

Voltage: 250V
Current: 16.0A at 30°C T-rise
Insulation Resistance: 5000 Megohms min.

Mechanical

Terminal Retention: 7.78 N (1.75 lbs) min.

Physical

Housing: LCP
Contact: Copper (Cu) Alloy
Plating:

Solder Tail Area – 100µ" Tin (Sn)

Underplating – 50µ" Nickel (Ni) overall

PCB Thickness:

Mother board – 1.57 to 3.18mm (.062 to .125")

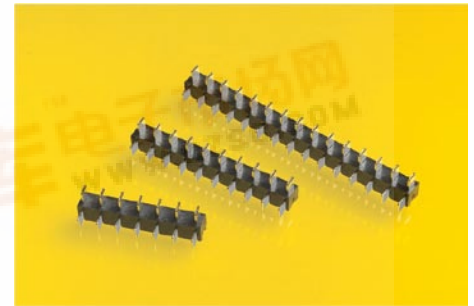
Daughter Card – 1.27 to 2.36mm (.050 to .093")

Operating Temperature: -40 to +105°C



4.00mm (.157") Pitch Micro-Max Power™ High-Current Header

75730 Board-to-Board



Left to right: 7, 10, and 15 circuit versions

APPLICATIONS

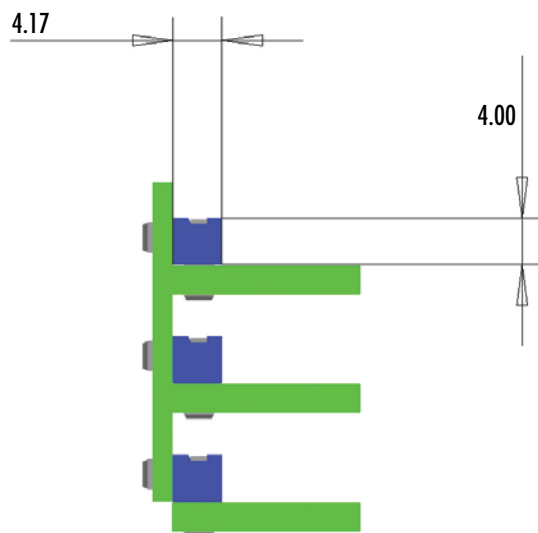
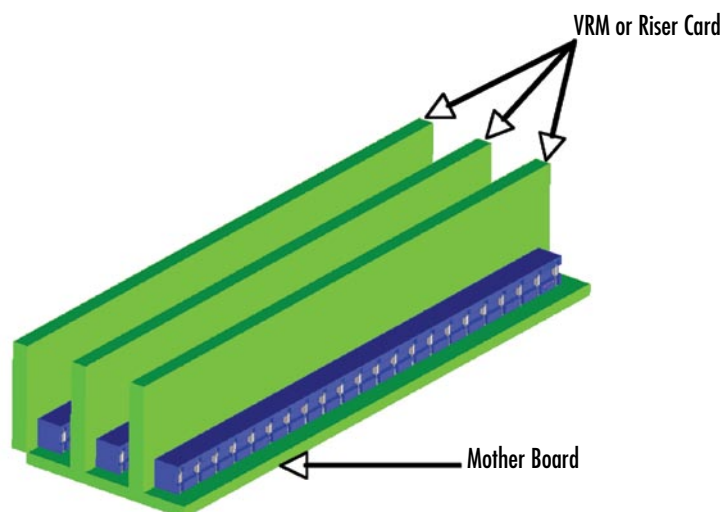
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4.00mm (.157") Pitch Micro-Max Power™ High-Current Header

75730 Board-to-Board

- VRM modules or any application for point-of-load power transfer
- Small Form Factor (SFF) PCs, workstations, servers, routers, switches, etc.



ORDERING INFORMATION

Order No. Mother Board : 3.06mm (.120") Tail Length	Circuit Size	Order No. Mother Board : 3.81mm (.150") Tail Length	Circuit Size
75730-0104	4	75730-0204	4
75730-0106	6	75730-0206	6
75730-0108	8	75730-0208	8
75730-0110	10	75730-0210	10
75730-0112	12	75730-0212	12
75730-0114	14	75730-0214	14
75730-0116	16	75730-0216	16
75730-0118	18	75730-0218	18
75730-0120	20	75730-0220	20
75730-0122	22	75730-0222	22
75730-0124	24	75730-0224	24
75730-0150	Voided Circuits	75730-0250	Voided Circuits

Note: Even circuit sizes shown above. Odd circuit sizes also available, please contact Molex.

Americas Headquarters
Lisle, Illinois 60532 U.S.A.
1-800-78MOLEX
amerinfo@molex.com

Asia Pacific North Headquarters
Yamato, Kanagawa, Japan
81-46-265-2325
apninfo@molex.com

Asia Pacific South Headquarters
Jurong, Singapore
65-6268-6868
fesinfo@molex.com

European Headquarters
Munich, Germany
49-89-413092-0
eurinfo@molex.com

Corporate Headquarters
2222 Wellington Ct.
Lisle, IL 60532 U.S.A.
630-969-4550
Fax: 630-969-1352

Visit our website at www.molex.com/product/micromaxpower.html